



If it is weak to heat, you can put it later!

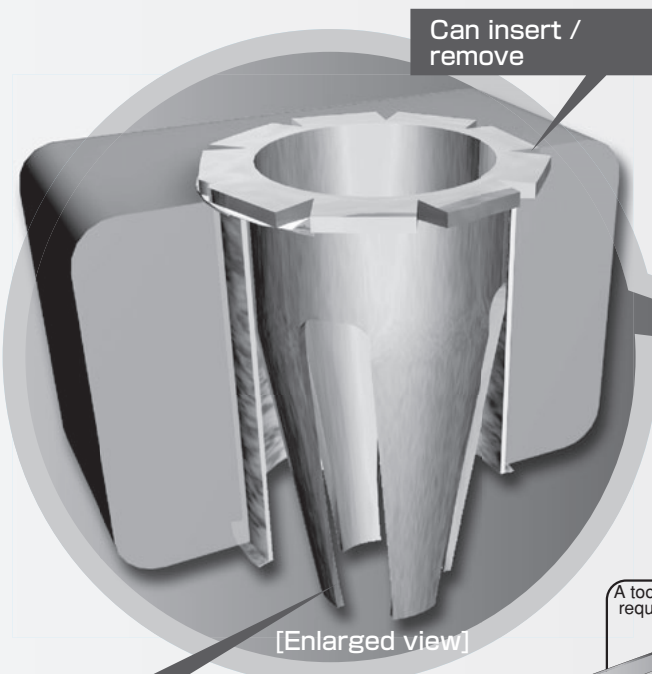
A through hole is changed to a socket!

Mr.Socket

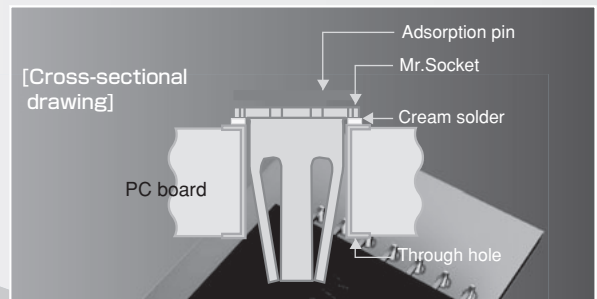
AF series

[Can be used by a chip mounter]

Parts can be fit without soldering.



Can be used for a chip mounter



A part which is weak to heat can be put on the PC board later!

A tool in response to many requests is now available!
Tool for pulling out adsorption pin for AF series
Model: AF-JIG

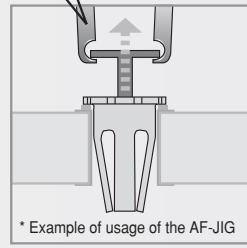
A through hole can be changed to a socket. It can be inserted / removed.



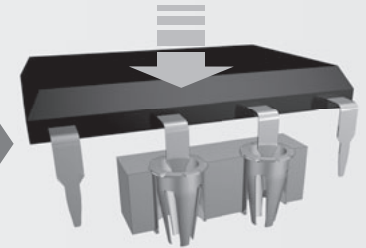
Automatic mounting by a chip mounter



Soldering by reflow



* Example of usage of the AF-JIG
Remove the adsorption pin. (Push from the back side and remove vertically.)



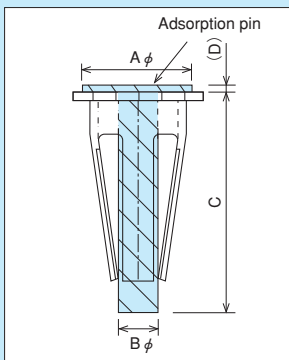
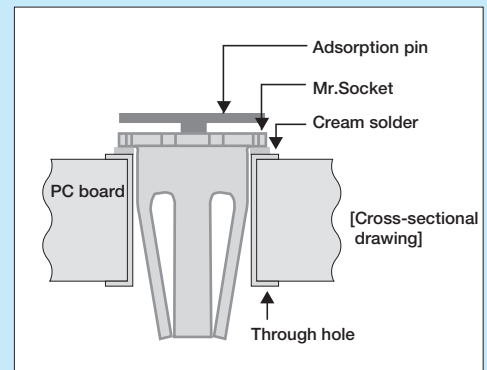
A through hole changes to a socket.

Socket pin

A through hole changes to a socket.

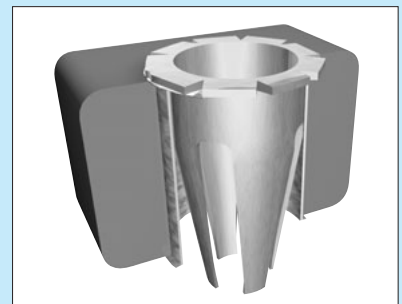
Mr.Socket [AF series]

- Just by automatically mounting the AF series to a through hole by a mounter and carrying out reflow, a through hole changes to a socket.
- Parts can be protected from the heat increase due to lead free soldering.
- Various parts (wire diameter: ϕ 0.40 to ϕ 1.0) can be mounted.
- Material: Beryllium copper (Adsorption pin: aluminum)
- Finish: Gold plating over nickel base
- Contact resistance: 10m Ω or less
- Rated current:
 - AF-0.5 () ... 2A
 - AF-0.7 () ... 4A
 - AF-0.9 () ... 6A
- Insertion /removal frequency: 100 times or less
- Recommended metal mask thickness: 100 to 150 μ
- Adaptive thickness of PC board: Any thickness
- Operating temperature range: -40 to +125 $^{\circ}$ C
- Please use the automatic recognition type of automatic mounter.



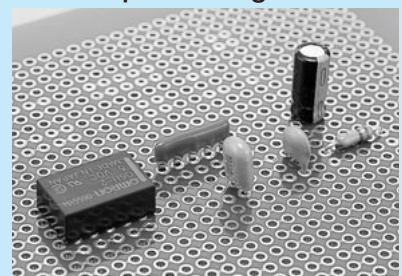
Adsorption pin state

Part number	A	B	C	(D)
AF-0.5 ()	1.3	0.45	2.9	0.18
AF-0.7 ()	1.6	0.6	3.4	0.15
AF-0.9 ()	2.0	0.8	4.0	0.25



Socket pin

Example of usage



Jig for pulling out adsorption pins

Part number:
AF-JIG (1 unit is included in 1 pack.)



Part number

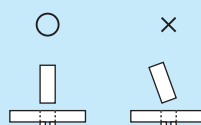
Part number	Adaptive male pin diameter	Insertion forces (average value: g)	Removal forces (average value: g)	Package state
AF-0.5(L)	ϕ 0.45 to ϕ 0.6	50	30	1000pcs/reel
AF-0.5(H)	ϕ 0.40 to ϕ 0.6	250	130	1000pcs/reel
AF-0.7(L)	ϕ 0.6 to ϕ 0.8	90	50	1000pcs/reel
AF-0.7(H)	ϕ 0.6 to ϕ 0.8	700	530	1000pcs/reel
AF-0.9(L)	ϕ 0.8 to ϕ 1.0	100	70	450pcs/reel
AF-0.9(H)	ϕ 0.8 to ϕ 1.0	280	200	450pcs/reel

- (L): Type with weak insertion/removal forces
- (H): Type with strong insertion/removal forces
- The insertion/removal forces described above indicate the value with the male pin center one.
- We offer them by bulk package. (It does not include adsorption pins.)
Example of bulk package part number: AF-0.5(L)-B (100 pieces are included in 1 pack.)

⤴ Please put "B" .

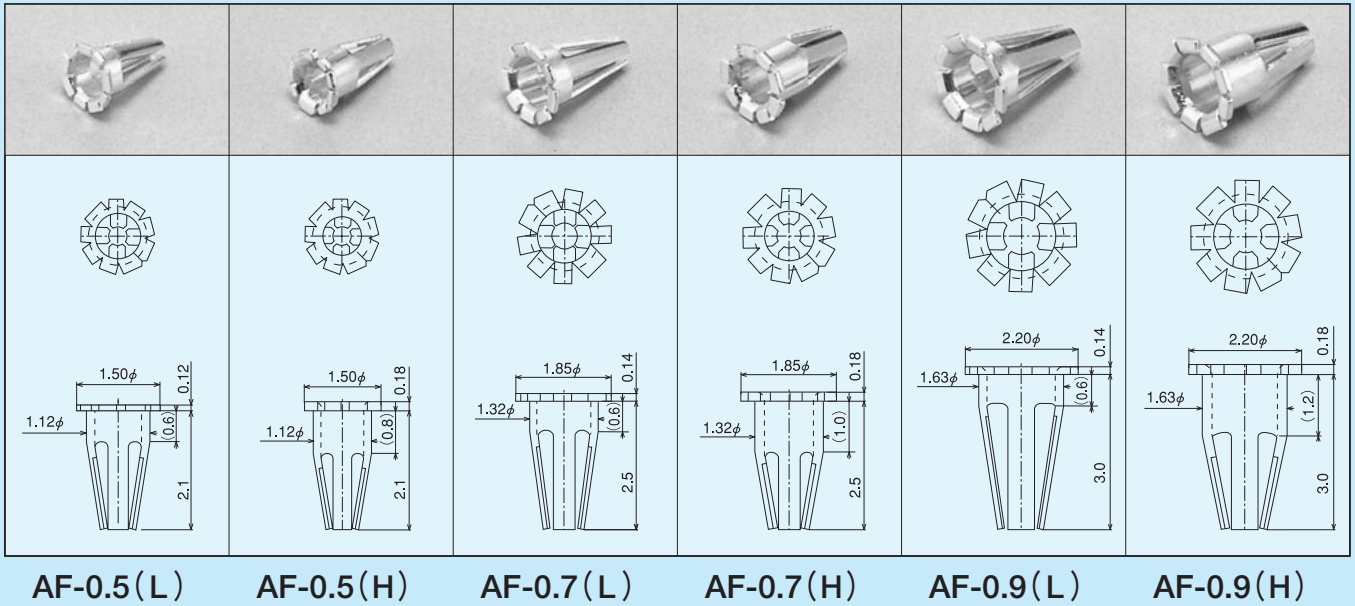
Instructions for use

Insert a male pin vertically.
Do not twist it to the left and right after inserting.
(It weakens the insertion/removal forces.)

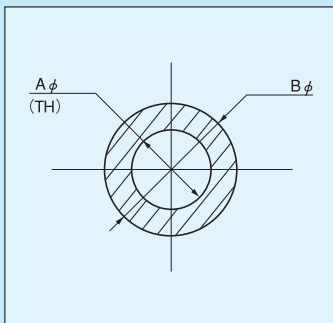


Various parts can be mounted.

Dimension



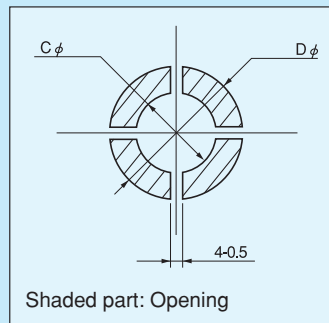
Recommended fitting land



Part number	+0.1 -0	
	A φ	B φ
AF-0.5 ()	1.2	2.0
AF-0.7 ()	1.4	2.5
AF-0.9 ()	1.7	3.0

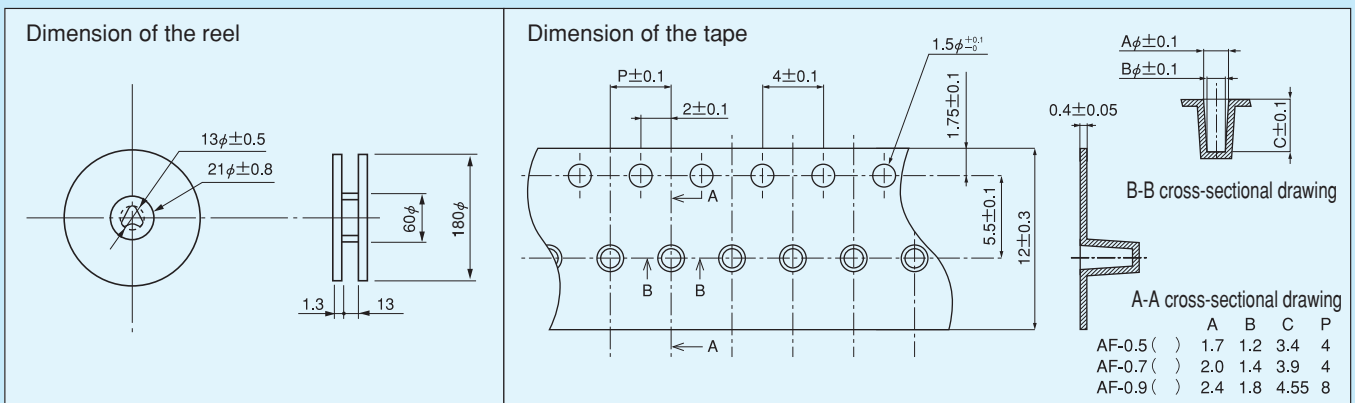
Recommended metal mask

(Recommended metal mask thickness: 100 to 150 μ) Solder Copper TH



Part number	TH board Gold TH board		
	C φ	C φ	D φ
AF-0.5 ()	1.5	1.3	2.0
AF-0.7 ()	1.7	1.5	2.5
AF-0.9 ()	2.0	1.8	3.0

Dimension of the reel



Process

1. Apply cream solder on PC board with a metal mask (recommended metal mask thickness: 100 to 150 μ)
2. Mount AF Series by a moulder (Please use automatic recognition type moulder).
3. Reflow.
4. Push the adsorption pin from the back side.
5. Remove the protruded adsorption pin straight by AF-JIG. (Do not twist it to the left and right.)

(Jig part number: AF-JIG) (1 unit is included in 1 pack.)